21st European Wet & 50th European CMP User Group Meeting

Wet- and CMP-Session: Thursday, April 23, 2026, 13:00 – 18:00

CMP-Session: Friday, April 24, 2026, 8:00 – 13:00

Hotel Dormero, Halle (Saale), Germany

Organized by European CMP&WET User Group and supported by SONOTEC

Agenda Thursday, April 23rd

12:00 – 13:30 Welcome Coffee, Tea, Softdrinks and Snacks

13:30 Opening Remarks & Welcome
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

Wet Session 1

Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:40 Theoretical Consideration of the Speed of Sound Influence on Ultrasonic Sensors in Liquids
Maik Christl
SONOTEC GmbH, Halle (Saale), Germany

14:05 Evaluating Non-TMAH Solvents for Sustainable Stripping of Photoresist Materials
Salem Nasraoui[1], Ronny Tepper[1], Katharina Lilienthal[2], Steffen Rosenow[1], Celin Richter[1]
[1]intelligent fluids, Leipzig, Germany, [2]Fraunhofer IPMS, Dresden Germany

14:30 Brasable Metal Full Wet Etch Process Optimization on SiC
Dario Tenaglia
STMicroelectronics, Agrate, Italy

14:55 Integrated Inductive Metrology for Wet Chemical Processing — From Pre-Etch Qualification to Post-Etch Verification
Michael Hofmann, Daniel Schmidt, and Marcus Klein
SURAGUS GmbH, Dresden, Germany

15:10 Veeco WaferStorm: WaferEtch in Advanced Packaging Applications
Benedikt Risse
Veeco, Aschheim, Germany

15:25 Company Pitch
ProSys, Gold Sponsor
Igor Eichinger, ProSys, Campbell, CA, USA

15:30 Company Pitch
Sonotec, Co-Organizer
Sebastian Bürkmann, SONOTEC GmbH, Halle (Saale), Germany

15:35 **Coffee Break**

Wet Session 2 & CMP Session 1

Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

16:10 GreenICT: From TSV Cleaning to Testing a New DMSO/TMAH-Free Stripper for Packaging Applications
Maksym Myndyk, Catharina Rudolph, and Haci Osman Guevenc
Fraunhofer IZM-ASSID, Dresden, Germany

16:25 From CMP to Hybrid Bonding: High-Throughput AFM Metrology for Advanced Semiconductor Manufacturing
Christian Bippes, Carolina Paba, Hector Corte, Santiago Andany, Hans Gunstheimer, Jonathan Adams, and Dominik Ziegler
Nanosurf, Liestal, Switzerland

16:50 A Planarization System Roadmap for Broadening Device Applications
Ji-Chul Yang
Ebara, Fujisawa, Japan

17:15 Advanced Node Process Characterization: Novel Chemical Mechanical Polishing with Environmentally Friendly Abrasive-Free Setup
Felix Köhler[1], Matthias Stender[2], Nikunjkumar Visaveliya[2], and Conrad Guhl[1]
[1]Fraunhofer IPMS, Dresden, Germany, [2]ChEmpower Corporation, Portland, OR, USA

17:40 End of Wet Users Meeting / time for networking and discussion

18:15 Bus Transfer to SONOTEC

19:00 Evening Reception and Dinner at SONOTEC
Opening: Manuela Münch, Michael Münch, Sebastian Bürkmann, Constantin Bartnitzek

22:30 Bus Transfer back to Hotel Dormero

Agenda Friday, April 24th

8:30 – 9:00 Good Morning Coffee, Tea, Softdrinks

9:00 Opening Remarks: 50th CMP User Group Meeting – A Jubilee
Gerfried Zwicker, Knut Gottfried, Catharina Rudolph, and Martin Kulawski

CMP Session 2

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

9:20 Effluent Slurry Extraction and Analysis in Cu, ILD and Mo CMP During In-Situ Conditioning with Various Types of Gritted Diamond Discs
Ara Philipossian[1], Y. Sampurno[1], A. Warfield[2], S. Robles[2], C. Keating[2], and J.J. Keleher[2]
[1]Araca, Inc., Tucson, AZ, USA; [2]Lewis University, Romeoville, IL, USA

10:10	Optimization of CMP Process for Copper and SiCN Wafer Hybrid Bonding Mais Massarwa, Ali Roshanghias, Rodrigues Augusto Daniel, Azeem Syed Munir, and Su MeiRu Silicon Austria Labs, Villach, Austria / FH Münster, Germany
10:35	Image Segmentation - A New Method for Quality Control of High Porosity CMP Pads Yawen He Hubei Dinglong Co., Ltd., Wuhan, China
11:05	Company Pitch Ebara, Gold Sponsor Fabien Durix, Ebara Precision Machinery Europe, Hanau, Germany
11:10	**Coffee Break**

CMP Session 3

Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany

11:45	Knowledge-Enhanced Process Modelling for CMP Tom Rothe[1], Jan Langer[2], and Harald Kuhn[2] [1]Chemnitz University of Technology, [2]Fraunhofer ENAS, Chemnitz, Germany
12:10	From Surface Topology to Surface Function: Phase-Space Projections of CMP Process Signatures in a Multiscale Framework Boris Brodmann OptoSurf, Ettlingen, Germany
12:35	Smarter CMP Control Through Virtual Metrology Andre Lauff[1], Morten Breidung[1], Peter Thieme[1], and Tom Rothe[2] [1]Infineon Technologies, Dresden, Germany, [2]Chemnitz University of Technology, Chemnitz, Germany
12:50	End of CMP User Group Meeting / Time for Networking and Discussion Coffee, Tea, Softdrinks, and Light Lunch